

30.5	29.3	25.65	24.5	54104-5031	50
28.5	27.3	23.65	22.5	54104-4631	46
28.0	26.8	23.15	22.0	54104-4531	45
27.5	26.3	22.65	21.5	54104-4431	44
27.0	25.8	22.15	21.0	54104-4331	43
25.5	24.3	20.65	19.5	54104-4031	40
24.5	23.3	19.65	18.5	54104-3831	38
23.5	22.3	18.65	17.5	54104-3631	36
23.0	21.8	18.15	17.0	54104-3531	35
22.5	21.3	17.65	16.5	54104-3431	34
22.0	20.8	17.15	16.0	54104-3331	33
21.5	20.3	16.65	15.5	54104-3231	32
20.5	19.3	15.65	14.5	54104-3031	30
D	C	B	A	EMBOSSED PACKAGE ORDER NO. オオーダー番号	CKT.

CONNECTOR SERIES NO. : 54104-\*\*-29

REVISED EC NO: J2012-1496 DRWN:KNAGUMO 2012/06/12 CHKD:KAKAHASHI 2012/06/12 APPR:KMORIKAWA 2012/06/12	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY MNABEI	DATE '04/07/09	TITLE 0.5 FPC CONN. ZIF SMT R/A UPPER CONTACT SEPARATED GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/07/09			
	30 OVER	±0.3	APPROVED BY NUKITA	DATE '04/07/09			
ANGULAR	±3 °	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-54104-077	SHEET NO. 1 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

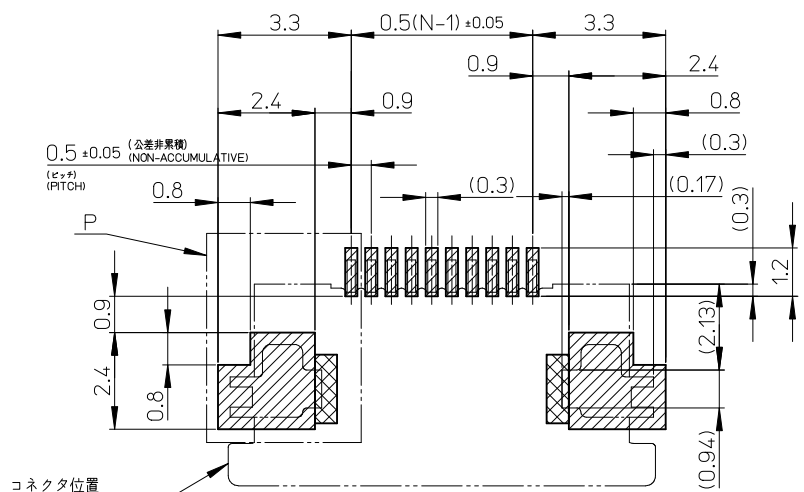
E

D

C

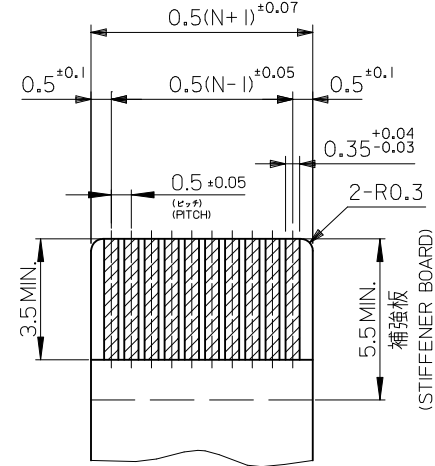
B

A



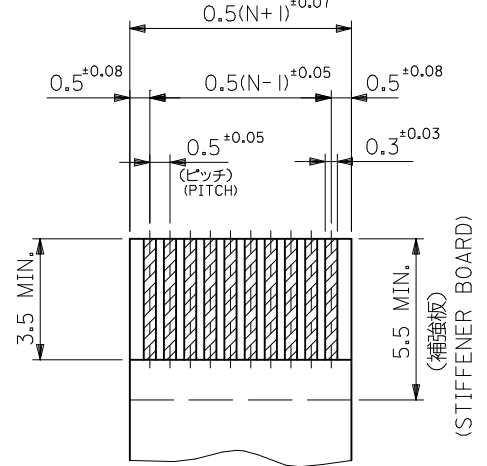
参考基板レイアウト  
RECOMMENDED P.W.BOARD PATTERN DIMENSION(REF.)

(マウント面)  
(MOUNTING SIDE)



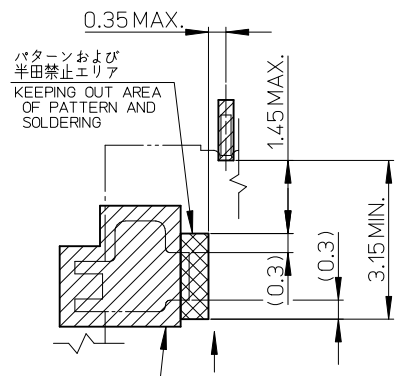
適合金めっきFPC推奨寸法  
APPLICABLE FPC OF GOLD PLATING  
RECOMMENDED DIMENSION

(仕上がり厚さ : 0.3 ± 0.03 )  
(THICKNESS : 0.3 ± 0.03)

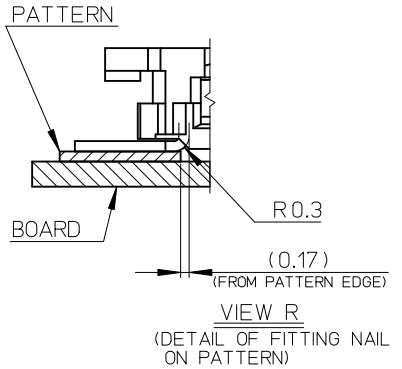


適合金めっきFFC推奨寸法  
APPLICABLE FFC OF GOLD PLATING  
RECOMMENDED DIMENSION

(仕上がり厚さ : 0.3 ± 0.03 )  
(THICKNESS : 0.3 ± 0.03)



DETAIL P



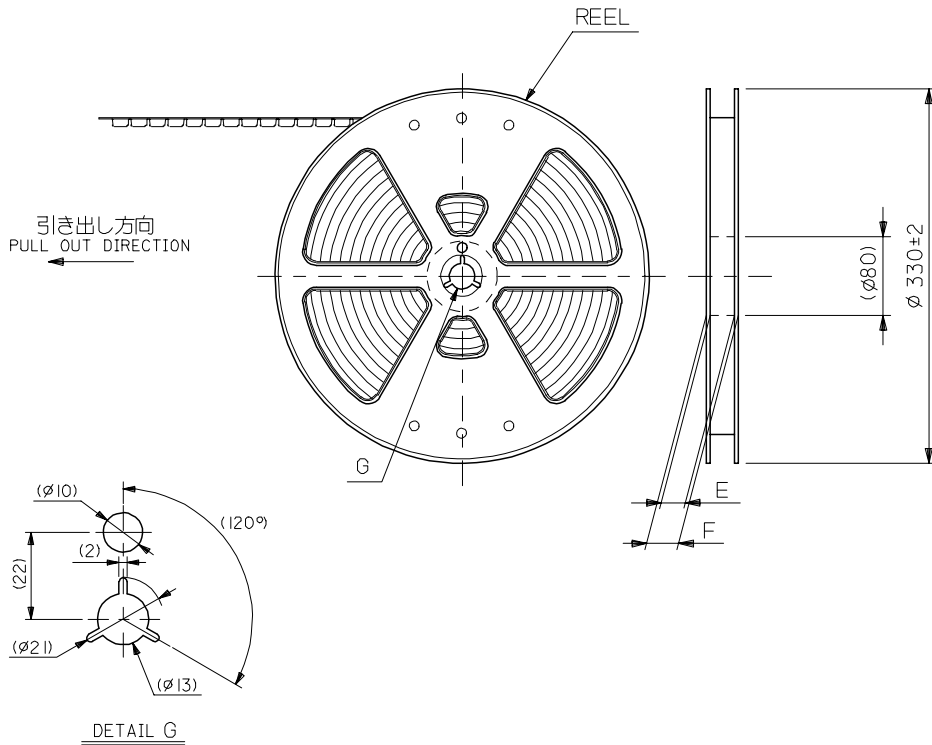
VIEW R  
(DETAIL OF FITTING NAIL  
ON PATTERN)

注記 NOTES

1. 使用材料 MATERIAL  
ハウジング : 46ナイロン、ガラス充填、UL94V-0、白  
HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE  
アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、茶色  
ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BROWN  
ターミナル : リン青銅 (t=0.2) 金メッキ コンタクト部 0.1 MICROMETER MINIMUM  
テール部 0.05 MICROMETER MINIMUM  
ニッケル下地 1.0 MICROMETER MINIMUM  
TERMINAL PHOS-BRONZE GOLD-PLATING  
CONTACT PORTION : 0.1 MICROMETER MINIMUM  
TAIL PORTION : 0.05 MICROMETER MINIMUM  
NICKEL PLATING : 1.0 MICROMETER MINIMUM  
金具 : リン青銅 (t=0.2) 錫メッキ 1.0~3.0 MICROMETER MINIMUM  
ニッケル下地 1.0~3.0 MICROMETER MINIMUM  
FITTING NAIL : PHOS-BRONZE TIN-PLATING 1.0~3.0 MICROMETER MINIMUM  
OVER NICKEL 1.0~3.0 MICROMETER MINIMUM
2. エンボステープ梱包時はアクチュエータがロックした状態とする。  
IN THE PACKAGE, ACTUATOR OF PART NO.54104-\*\*\*29 SHOULD BE LOCKED.  
ソルダータール半田付け面のズレ量、および金具半田付け面のズレ量は  
基準面 (H) に対し上方向 0.1MAXIMUM、下方向 0.15MAXIMUMとする。  
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM (H)  
UPPER DIRECTION : 0.1MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.

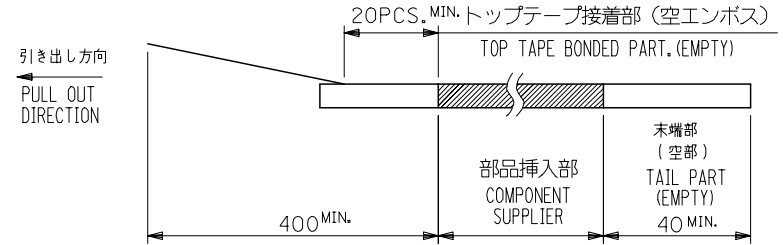
- △4 偶数極に適用。  
APPLY FOR EVEN CIRCUIT.
  - △5 パターンはく離止め金具。  
FITTING NAIL FOR PREVENTION OF PEELING OF P.W.BOARD PATTERN.
  - 6. ELV & RoHS適合品  
ELV AND RoHS COMPLIANT
- FPC/FFCについて：  
打ち抜き方向は導体側から補強板側を推奨いたします。  
導体部は軟銅箔 35MICROMETER または 50MICROMETERを推奨いたします。  
RECOMMENDED PUNCHER DIRECTION FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED CONDUCTOR SPEC THICKNESS OF SOFT COPPER FOIL : 35MICROMETERS OR 50MICROMETERS
- FPCについて：  
補強フィルム材質はポリイミドを推奨いたします。  
接着剤は熱硬化接着剤を推奨いたします。  
RECOMMENDED MATERIAL STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2012-1496 DRWN:KNAGIMO 2012/06/12 CHKD:KAKAHASHI 2012/06/12 APP:R:KMORI/KAWA 2012/06/12	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY MNABEI	DATE '04/07/09	TITLE 0.5 FPC CONN. ZIF SMT R/A UPPER CONTACT SEPARATED GOLD PLATING			
	10 OVER 30 UNDER	± ---	CHECKED BY KTOJO	DATE '04/07/09				
	30 OVER	± ---	APPROVED BY NUKITA	DATE '04/07/09				
ANGULAR	± --- °	MATERIAL NO. SEE SHEET 1 OF 2		DOCUMENT NO. SD-54104-077		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



NOTES

1. 梱包数量：1500個/リール  
NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH

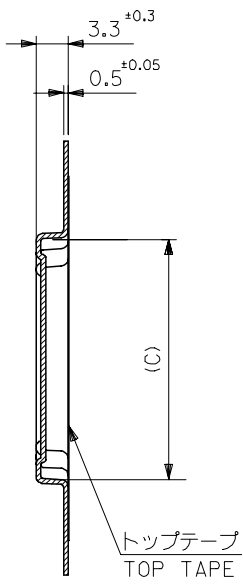


3. 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOPTAPE) : PET , PE , PEF  
リール (REEL) : ポリスチレン (POLYSTYLENE)
4. 本製品は 54104-\*\*-96 のターミナル部分全メッキ品である。

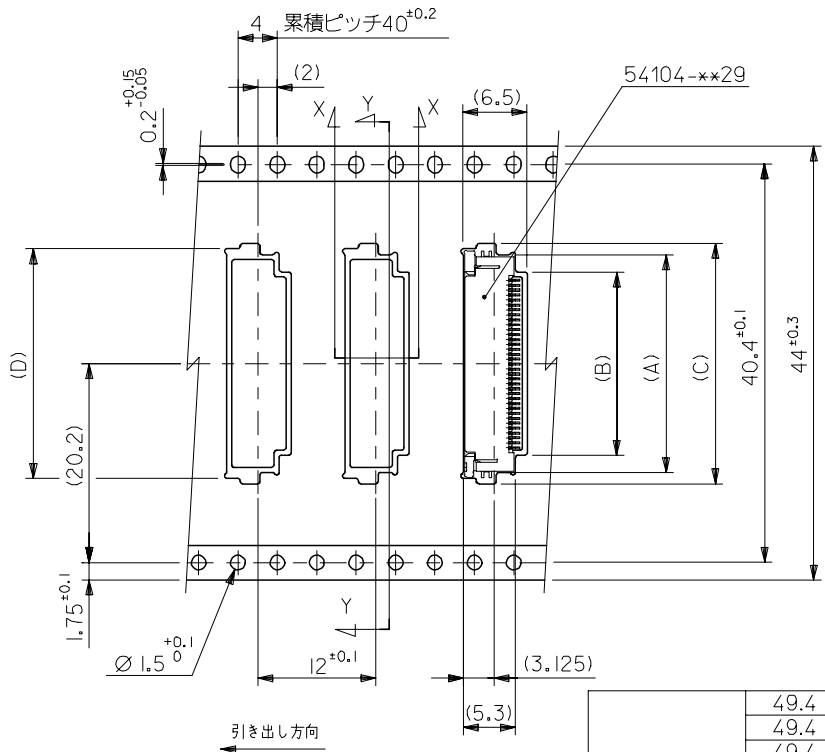
REVISED EC NO: J2007-2009 DRWN: YAMADA01 2007/01/23 CHKD: TOYODA 2007/01/25 APPR: NUKITA 2007/01/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY MNABEI	DATE '04/07/09	TITLE EMBOSSD TAPE PACKAGE FOR 54104-**-29 -LEAD FREE-	
	10 OVER 30 UNDER	± 0.25	CHECKED BY KTOJO	DATE '04/07/09	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY NUKITA	DATE '04/07/09		
ANGULAR ± 3 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-54104-078	SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1

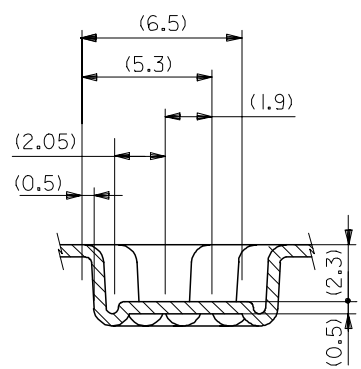
F  
E  
D  
C  
B  
A



SECT:Y-Y



引き出し方向



44	49.4	45.4	30.8	31.9	26.1	29.6	54104-5031	50
	49.4	45.4	28.8	29.9	24.1	27.6	54104-4631	46
	49.4	45.4	28.3	29.4	23.6	27.1	54104-4531	45
	49.4	45.4	27.8	28.9	23.1	26.6	54104-4431	44
	49.4	45.4	27.3	28.4	22.6	26.1	54104-4331	43
	49.4	45.4	25.8	26.9	21.1	24.6	54104-4031	40
	49.4	45.4	24.8	25.9	20.1	23.6	54104-3831	38
	49.4	45.4	23.8	24.9	19.1	22.6	54104-3631	36
	49.4	45.4	23.3	24.4	18.6	22.1	54104-3531	35
	49.4	45.4	22.8	23.9	18.1	21.6	54104-3431	34
	49.4	45.4	22.3	23.4	17.6	21.1	54104-3331	33
	49.4	45.4	21.8	22.9	17.1	20.6	54104-3231	32
49.4	45.4	20.8	21.9	16.1	19.6	54104-3031	30	
キャリアテープ幅 CARRIER TAPE WIDTH	F	E	D	C	B	A	MATERIAL NO.	CKT.

REVISED EC NO: J2007-2009 DRWN: YAMADA01 2007/01/23 CHKD: KTOYODA 2007/01/25 APPR: NUKITA 2007/01/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY MNABEI	DATE '04/07/09	TITLE EMBOSSED TAPE PACKAGE FOR 54104-**-29 -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/07/09				
	30 OVER	±0.3	APPROVED BY NUKITA	DATE '04/07/09	MOLEX INCORPORATED MATERIAL NO. SEE CHART DOCUMENT NO. SD-54104-078 SHEET NO. 2 OF 2			
ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						